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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Discontinued at Digi-Key
Core Processor	8051
Core Size	8-Bit
Speed	48 MIPS
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	25
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2.25К х 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.25V
Data Converters	A/D 21x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f38b-gqr

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Name	Pin Nu	mbers	Туре	Description
	48-pin	32-pin		
P3.2	28	_	D I/O or A In	Port 3.2.
P3.3	27		D I/O or A In	Port 3.3.
P3.4	26	_	D I/O or A In	Port 3.4.
P3.5	25	_	D I/O or A In	Port 3.5.
P3.6	24	_	D I/O or A In	Port 3.6.
P3.7	23		D I/O or A In	Port 3.7.
P4.0	22	_	D I/O or A In	Port 4.0. See Section 20 for a complete description of Port 4.
P4.1	21	_	D I/O or A In	Port 4.1.
P4.2	20	_	D I/O or A In	Port 4.2.
P4.3	19	_	D I/O or A In	Port 4.3.
P4.4	18	_	D I/O or A In	Port 4.4.
P4.5	17	_	D I/O or A In	Port 4.5.
P4.6	16	—	D I/O or A In	Port 4.6.
P4.7	15	_	D I/O or A In	Port 4.7.

Table 3.1. Pin Definitions for the C8051F388/9/A/B (Continued)



6.3.3. Settling Time Requirements

A minimum tracking time is required before each conversion to ensure that an accurate conversion is performed. This tracking time is determined by the AMUX0 resistance, the ADC0 sampling capacitance, any external source resistance, and the accuracy required for the conversion. Note that in low-power tracking mode, three SAR clocks are used for tracking at the start of every conversion. For most applications, these three SAR clocks will meet the minimum tracking time requirements.

Figure 6.5 shows the equivalent ADC0 input circuit. The required ADC0 settling time for a given settling accuracy (SA) may be approximated by Equation 6.1. See Table 5.10 for ADC0 minimum settling time requirements as well as the mux impedance and sampling capacitor values.



Equation 6.1. ADC0 Settling Time Requirements

Where:

SA is the settling accuracy, given as a fraction of an LSB (for example, 0.25 to settle within 1/4 LSB) *t* is the required settling time in seconds

 R_{TOTAL} is the sum of the AMUX0 resistance and any external source resistance. *n* is the ADC resolution in bits (10).

Differential Mode

Single-Ended Mode





Figure 6.5. ADC0 Equivalent Input Circuits

Rev. 1.1



11. CIP-51 Microcontroller

The MCU system controller core is the CIP-51 microcontroller. The CIP-51 is fully compatible with the MCS-51[™] instruction set; standard 803x/805x assemblers and compilers can be used to develop software. The MCU family has a superset of all the peripherals included with a standard 8051. The CIP-51 also includes on-chip debug hardware (see description in Section 27), and interfaces directly with the analog and digital subsystems providing a complete data acquisition or control-system solution in a single integrated circuit.

The CIP-51 Microcontroller core implements the standard 8051 organization and peripherals as well as additional custom peripherals and functions to extend its capability (see Figure 11.1 for a block diagram). The CIP-51 includes the following features:

- Fully Compatible with MCS-51 Instruction Set
- 48 MIPS Peak Throughput with 48 MHz Clock
- 0 to 48 MHz Clock Frequency
- Extended Interrupt Handler

- Reset Input
- Power Management Modes
- On-chip Debug Logic
- Program and Data Memory Security

Performance

The CIP-51 employs a pipelined architecture that greatly increases its instruction throughput over the standard 8051 architecture. In a standard 8051, all instructions except for MUL and DIV take 12 or 24 system clock cycles to execute, and usually have a maximum system clock of 12 MHz. By contrast, the CIP-51 core executes 70% of its instructions in one or two system clock cycles, with no instructions taking more than eight system clock cycles.



Figure 11.1. CIP-51 Block Diagram



Table 11.1. CIP-51 Instruction Set Summary (Continued)

Mnemonic	Description	Bytes	Clock Cycles
XRL direct, #data	Exclusive-OR immediate to direct byte	3	3
CLR A	Clear A	1	1
CPLA	Complement A	1	1
RL A	Rotate A left	1	1
RLC A	Rotate A left through Carry	1	1
RR A	Rotate A right	1	1
RRC A	Rotate A right through Carry	1	1
SWAP A	Swap nibbles of A	1	1
Data Transfer			
MOV A, Rn	Move Register to A	1	1
MOV A, direct	Move direct byte to A	2	2
MOVA, @Ri	Move indirect RAM to A	1	2
MOV A, #data	Move immediate to A	2	2
MOV Rn, A	Move A to Register	1	1
MOV Rn, direct	Move direct byte to Register	2	2
MOV Rn, #data	Move immediate to Register	2	2
MOV direct, A	Move A to direct byte	2	2
MOV direct. Rn	Move Register to direct byte	2	2
MOV direct, direct	Move direct byte to direct byte	3	3
MOV direct. @Ri	Move indirect RAM to direct byte	2	2
MOV direct, #data	Move immediate to direct byte	3	3
MOV @Ri, A	Move A to indirect RAM	1	2
MOV @Ri, direct	Move direct byte to indirect RAM	2	2
MOV @Ri, #data	Move immediate to indirect RAM	2	2
MOV DPTR, #data16	Load DPTR with 16-bit constant	3	3
MOVC A, @A+DPTR	Move code byte relative DPTR to A	1	3
MOVCA, @A+PC	Move code byte relative PC to A	1	3
MOVX A, @Ri	Move external data (8-bit address) to A	1	3
MOVX @Ri, A	Move A to external data (8-bit address)	1	3
MOVX A, @DPTR	Move external data (16-bit address) to A	1	3
MOVX @DPTR, A	Move A to external data (16-bit address)	1	3
PUSH direct	Push direct byte onto stack	2	2
POP direct	Pop direct byte from stack	2	2
XCH A, Rn	Exchange Register with A	1	1
XCH A, direct	Exchange direct byte with A	2	2
XCH A, @Ri	Exchange indirect RAM with A	1	2
XCHD A, @Ri	Exchange low nibble of indirect RAM with A	1	2
Boolean Manipulation			
CLR C	Clear Carry	1	1
CLR bit	Clear direct bit	2	2
SETB C	Set Carry	1	1
SETB bit	Set direct bit	2	2
CPL C	Complement Carry	1	1
CPL bit	Complement direct bit	2	2



SFR Definition 18.1. PSCTL: Program Store R/W Control

Bit	7	6	5	4	3	2	1	0
Name							PSEE	PSWE
Туре	R	R	R	R	R	R	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address =0x8F; SFR Page = All Pages

Bit	Name	Function
7:2	Reserved	Must write 000000b.
1	PSEE	Program Store Erase Enable.
		Setting this bit (in combination with PSWE) allows an entire page of Flash program memory to be erased. If this bit is logic 1 and Flash writes are enabled (PSWE is logic 1), a write to Flash memory using the MOVX instruction will erase the entire page that contains the location addressed by the MOVX instruction. The value of the data byte written does not matter. 0: Flash program memory erasure disabled. 1: Flash program memory erasure enabled.
0	PSWE	Program Store Write Enable.
		 Setting this bit allows writing a byte of data to the Flash program memory using the MOVX write instruction. The Flash location should be erased before writing data. 0: Writes to Flash program memory disabled. 1: Writes to Flash program memory enabled; the MOVX write instruction targets Flash memory.



19.4. Programmable Internal Low-Frequency (L-F) Oscillator

All C8051F388/9/A/B devices include a programmable low-frequency internal oscillator, which is calibrated to a nominal frequency of 80 kHz. The low-frequency oscillator circuit includes a divider that can be changed to divide the clock by 1, 2, 4, or 8, using the OSCLD bits in the OSCLCN register (see SFR Definition 19.5). Additionally, the OSCLF[3:0] bits can be used to adjust the oscillator's output frequency.

19.4.1. Calibrating the Internal L-F Oscillator

Timers 2 and 3 include capture functions that can be used to capture the oscillator frequency, when running from a known time base. When either Timer 2 or Timer 3 is configured for L-F Oscillator Capture Mode, a falling edge (Timer 2) or rising edge (Timer 3) of the low-frequency oscillator's output will cause a capture event on the corresponding timer. As a capture event occurs, the current timer value (TMRnH:TMRnL) is copied into the timer reload registers (TMRnRLH:TMRnRLL). By recording the difference between two successive timer capture values, the low-frequency oscillator's period can be calculated. The OSCLF bits can then be adjusted to produce the desired oscillator frequency.

SFR Definition 19.5. OSCLCN: Internal L-F Oscillator Control

Bit	7	6	5	4	3	2	1	0
Name	OSCLEN	OSCLRDY	OSCLF[3:0]				OSCL	D[1:0]
Туре	R/W	R		R.	R/	W		
Reset	0	0	Varies	Varies	Varies	Varies	0	0

SFR Address = 0x86; SFR Page = All Pages

Bit	Name	Function
7	OSCLEN	Internal L-F Oscillator Enable.
		0: Internal L-F Oscillator Disabled.
		1: Internal L-F Oscillator Enabled.
6	OSCLRDY	Internal L-F Oscillator Ready.
		0: Internal L-F Oscillator frequency not stabilized.
		1: Internal L-F Oscillator frequency stabilized.
		Note: OSCLRDY is only set back to 0 in the event of a device reset or a change to the OSCLD[1:0] bits.
5:2	OSCLF[3:0]	Internal L-F Oscillator Frequency Control Bits.
		Fine-tune control bits for the Internal L-F oscillator frequency. When set to 0000b, the L-F oscillator operates at its fastest setting. When set to 1111b, the L-F oscillator operates at its slowest setting. The OSCLF bits should only be changed by firmware when the L-F oscillator is disabled (OSCLEN = 0).
1:0	OSCLD[1:0]	Internal L-F Oscillator Divider Select.
		00: Divide by 8 selected.
		01: Divide by 4 selected.
		10: Divide by 2 selected.
		11: Divide by 1 selected.



SFR Definition 19.6. OSCXCN: External Oscillator Control

Bit	7	6	5	4	3	2	1	0
Name	XCLKVLD	×	(OSCMD[2:0)]			XFCN[2:0]	
Туре	R		R/W				R/W	
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xB1; SFR Page = All Pages

Bit	Name		Function						
7	XCLKVLD	Externa Provide tion exc divide b 0: Exter 1: Exter	 xternal Oscillator Valid Flag. rovides External Oscillator status and is valid at all times for all modes of opera- on except External CMOS Clock Mode and External CMOS Clock Mode with ivide by 2. In these modes, XCLKVLD always returns 0. External Oscillator is unused or not yet stable. External Oscillator is running and stable. 						
6:4	XOSCMD[2:0]	Externa 00x: Ext 010: Ex 011: Ext 100: RC 101: Ca 110: Cry 111: Cry	 External Oscillator Mode Select. 10x: External Oscillator circuit off. 110: External CMOS Clock Mode. 111: External CMOS Clock Mode with divide-by-2 stage. 00: RC Oscillator Mode with divide-by-2 stage. 01: Capacitor Oscillator Mode with divide-by-2 stage. 10: Crystal Oscillator Mode. 11: Crystal Oscillator Mode with divide-by-2 stage. 						
3	Unused	Read =	Read = 0; Write = don't care						
2:0	XFCN[2:0]	Externa Set acco Set acco	External Oscillator Frequency Control Bits. Set according to the desired frequency for RC mode. Set according to the desired K Factor for C mode.						
		XFCN Crystal Mode RC Mode C Mode							
		000	f ≤ 20 kHz	f ≤ 25 kHz	K Factor = 0.87				
		001	20 kHz < f ≤ 58 kHz	25 kHz < f \leq 50 kHz	K Factor = 2.6				
		010	58 kHz < f ≤ 155 kHz	50 kHz < f \leq 100 kHz	K Factor = 7.7				
		011	155 kHz < f ≤ 415 kHz	100 kHz $<$ f \leq 200 kHz	K Factor = 22				
		100	415 kHz $< f \le 1.1$ MHz	$200 \text{ kHz} < f \le 400 \text{ kHz}$	K Factor = 65				
		101	1.1 MHz $< f \le 3.1$ MHz	400 kHz $< f \le 800$ kHz	K Factor = 180				
		110	3.1 MHz $< f \le 8.2$ MHz	800 kHz < f \leq 1.6 MHz	K Factor = 664				
		111	$8.2 \text{ MHz} < f \le 25 \text{ MHz}$	$1.6 \text{ MHz} < f \leq 3.2 \text{ MHz}$	K Factor = 1590				



SFR Definition 20.2. XBR1: Port I/O Crossbar Register 1

Bit	7	6	5	4	3	2	1	0
Name	WEAKPUD	XBARE	T1E	T0E	ECIE	F	PCA0ME[2:0]
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xE2; SFR Page = All Pages

Bit	Name	Function
7	WEAKPUD	Port I/O Weak Pullup Disable.
		0: Weak Pullups enabled (except for Ports whose I/O are configured for analog
		mode).
		1: Weak Pullups disabled.
6	XBARE	Crossbar Enable.
		0: Crossbar disabled.
		1: Crossbar enabled.
5	T1E	T1 Enable.
		0: T1 unavailable at Port pin.
		1: T1 routed to Port pin.
4	T0E	T0 Enable.
		0: T0 unavailable at Port pin.
		1: T0 routed to Port pin.
3	ECIE	PCA0 External Counter Input Enable.
		0: ECI unavailable at Port pin.
		1: ECI routed to Port pin.
2:0	PCA0ME[2:0]	PCA Module I/O Enable Bits.
		000: All PCA I/O unavailable at Port pins.
		001: CEX0 routed to Port pin.
		010: CEX0, CEX1 routed to Port pins.
		011: CEX0, CEX1, CEX2 routed to Port pins.
		100: CEX0, CEX1, CEX2, CEX3 routed to Port pins.
		101: CEX0, CEX1, CEX2, CEX3 routed to Port pins.
		11x: Reserved.



21.5. SMBus Transfer Modes

The SMBus interface may be configured to operate as master and/or slave. At any particular time, it will be operating in one of the following four modes: Master Transmitter, Master Receiver, Slave Transmitter, or Slave Receiver. The SMBus interface enters Master Mode any time a START is generated, and remains in Master Mode until it loses an arbitration or generates a STOP. An SMBus interrupt is generated at the end of all SMBus byte frames. The position of the ACK interrupt when operating as a receiver depends on whether hardware ACK generation is enabled. As a receiver, the interrupt for an ACK occurs **before** the ACK with hardware ACK generation disabled, and **after** the ACK when hardware ACK generation is enabled. As a transmitter, interrupts occur **after** the ACK, regardless of whether hardware ACK generation is enabled or not.

21.5.1. Write Sequence (Master)

During a write sequence, an SMBus master writes data to a slave device. The master in this transfer will be a transmitter during the address byte, and a transmitter during all data bytes. The SMBus interface generates the START condition and transmits the first byte containing the address of the target slave and the data direction bit. In this case the data direction bit (R/W) will be logic 0 (WRITE). The master then transmits one or more bytes of serial data. After each byte is transmitted, an acknowledge bit is generated by the slave. The transfer is ended when the STO bit is set and a STOP is generated. The interface will switch to Master Receiver Mode if SMB0DAT is not written following a Master Transmitter interrupt. Figure 21.5 shows a typical master write sequence. Two transmit data bytes are shown, though any number of bytes may be transmitted. Notice that all of the "data byte transferred" interrupts occur **after** the ACK cycle in this mode, regardless of whether hardware ACK generation is enabled.







22.2.2. 9-Bit UART

9-bit UART mode uses a total of eleven bits per data byte: a start bit, 8 data bits (LSB first), a programmable ninth data bit, and a stop bit. The state of the ninth transmit data bit is determined by the value in TB80 (SCON0.3), which is assigned by user software. It can be assigned the value of the parity flag (bit P in register PSW) for error detection, or used in multiprocessor communications. On receive, the ninth data bit goes into RB80 (SCON0.2) and the stop bit is ignored.

Data transmission begins when an instruction writes a data byte to the SBUF0 register. The TI0 Transmit Interrupt Flag (SCON0.1) is set at the end of the transmission (the beginning of the stop-bit time). Data reception can begin any time after the REN0 Receive Enable bit (SCON0.4) is set to 1. After the stop bit is received, the data byte will be loaded into the SBUF0 receive register if the following conditions are met: (1) RI0 must be logic 0, and (2) if MCE0 is logic 1, the 9th bit must be logic 1 (when MCE0 is logic 0, the state of the ninth data bit is unimportant). If these conditions are met, the eight bits of data are stored in SBUF0, the ninth bit is stored in RB80, and the RI0 flag is set to 1. A UART0 interrupt will occur if enabled when either TI0 or RI0 is set to 1.







SFR Definition 22.1. SCON0: Serial Port 0 Control

Bit	7	6	5	4	3	2	1	0
			5	-	5		•	•
Nam	e S0MOD	E -	MCE0	REN0	TB80	RB80	TIO	RI0
Тур	e R/W	R	R/W	R/W	R/W	R/W	R/W	R/W
Rese	et 0	1	0	0	0	0	0	0
SFR A	ddress = 0	(98; SFR Page	= All Pages	; Bit-Address	sable			
Bit	Name				Function			
7	SOMODE	Serial Port 0 Operation Mode. Selects the UART0 Operation Mode. 0: 8-bit UART with Variable Baud Rate. 1: 9-bit UART with Variable Baud Rate.						

		1: 9-bit UART with Variable Baud Rate.
6	Unused	Read = 1b, Write = don't care.
5	MCE0	Multiprocessor Communication Enable.
		The function of this bit is dependent on the Serial Port 0 Operation Mode:
		Mode 0: Checks for valid stop bit.
		0: Logic level of stop bit is ignored.
		1: RIO will only be activated if stop bit is logic level 1.
		Mode 1: Multiprocessor Communications Enable.
		U: Logic level of ninth bit is ignored.
	DENIO	T. Rio is set and an interrupt is generated only when the finith bit is logic 1.
4	REN0	
		0: UAR 10 reception disabled.
	TDaa	
3	I B80	Ninth Transmission Bit.
		The logic level of this bit will be sent as the ninth transmission bit in 9-bit UART Mode (Mode 1). Unused in 8-bit mode (Mode 0).
2	RB80	Ninth Receive Bit.
		RB80 is assigned the value of the STOP bit in Mode 0; it is assigned the value of the 9th data bit in Mode 1.
1	TI0	Transmit Interrupt Flag.
		Set by hardware when a byte of data has been transmitted by UART0 (after the 8th bit in 8-bit UART Mode, or at the beginning of the STOP bit in 9-bit UART Mode). When the UART0 interrupt is enabled, setting this bit causes the CPU to vector to the UART0 interrupt service routine. This bit must be cleared manually by software.
0	RI0	Receive Interrupt Flag.
		Set to 1 by hardware when a byte of data has been received by UART0 (set at the STOP bit sampling time). When the UART0 interrupt is enabled, setting this bit to 1 causes the CPU to vector to the UART0 interrupt service routine. This bit must be cleared manually by software.





* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.

Figure 24.10. SPI Slave Timing (CKPHA = 0)



* SCK is shown for CKPOL = 0. SCK is the opposite polarity for CKPOL = 1.





SFR Definition 25.10. TMR2RLL: Timer 2 Reload Register Low Byte

Bit	7	6	5	4	3	2	1	0
Name				TMR2F	RLL[7:0]			
Туре	R/W							
Reset	0	0	0	0	0	0	0	0
SFR Address = 0xCA; SFR Page = 0								

Bit	Name	Function
7:0	TMR2RLL[7:0]	Timer 2 Reload Register Low Byte.
		TMR2RLL holds the low byte of the reload value for Timer 2.

SFR Definition 25.11. TMR2RLH: Timer 2 Reload Register High Byte

Bit	7	6	5	4	3	2	1	0
Name TMR2RLH[7:0]								
Type R/W								
Rese	et 0	0	0	0	0	0	0	0
SFR A	Address = 0xCE	3; SFR Page	e = 0					
Bit	Name				Function			
7:0	TMR2RLH[7:0] Timer 2 I	Reload Regi	ster High B	yte.			
		TMR2RL	H holds the h	high byte of t	he reload va	alue for Time	r 2.	

SFR Definition 25.12. TMR2L: Timer 2 Low Byte

Bit	7	6	5	4	3	2	1	0
Name		TMR2L[7:0]						
Туре		R/W						
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xCC; SFR Page = 0

Bit	Name	Function
7:0	TMR2L[7:0]	Timer 2 Low Byte.
		In 16-bit mode, the TMR2L register contains the low byte of the 16-bit Timer 2. In 8- bit mode, TMR2L contains the 8-bit low byte timer value.



SFR Definition 25.15. TMR3RLL: Timer 3 Reload Register Low Byte

Bit	7	6	5	4	3	2	1	0
Nam	e	TMR3RLL[7:0]						
Туре	•			R/	W			
Rese	et 0	0	0	0	0	0	0	0
SFR Address = 0x92; SFR Page = 0								
Bit	Name				Function			

Bit	Name	Function
7:0	TMR3RLL[7:0]	Timer 3 Reload Register Low Byte.

TMR3RLL holds the low byte of the reload value for Timer 3.

SFR Definition 25.16. TMR3RLH: Timer 3 Reload Register High Byte

Bit	7	6	5	4	3	2	1	0
Name TMR3RLH[7:0]								
Тур	pe R/W							
Rese	et 0	0	0	0	0	0	0	0
SFR A	Address = 0x93	; SFR Page	= 0					
Bit	Name				Function			
7:0	TMR3RLH[7:0] Timer 3 I	Reload Regi	ister High B	yte.			
		TMR3RLH holds the high byte of the reload value for Timer 3.						

SFR Definition 25.17. TMR3L: Timer 3 Low Byte

Bit	7	6	5	4	3	2	1	0
Name		TMR3L[7:0]						
Туре		R/W						
Reset	0	0	0	0	0	0	0	0

SFR Address = 0x94; SFR Page = 0

Bit	Name	Function
7:0	TMR3L[7:0]	Timer 3 Low Byte.
		In 16-bit mode, the TMR3L register contains the low byte of the 16-bit Timer 3. In 8-bit mode, TMR3L contains the 8-bit low byte timer value.



26.2. PCA0 Interrupt Sources

Figure 26.3 shows a diagram of the PCA interrupt tree. There are six independent event flags that can be used to generate a PCA0 interrupt. They are: the main PCA counter overflow flag (CF), which is set upon a 16-bit overflow of the PCA0 counter and the individual flags for each PCA channel (CCF0, CCF1, CCF2, CCF3, and CCF4), which are set according to the operation mode of that module. These event flags are always set when the trigger condition occurs. Each of these flags can be individually selected to generate a PCA0 interrupt, using the corresponding interrupt enable flag (ECF for CF, and ECCFn for each CCFn). PCA0 interrupts must be globally enabled before any individual interrupt sources are recognized by the processor. PCA0 interrupts are globally enabled by setting the EA bit and the EPCA0 bit to logic 1.



Figure 26.3. PCA Interrupt Block Diagram



SFR Definition 26.3. PCA0CPMn: PCA Capture/Compare Mode

Bit	7	6	5	4	3	2	1	0
Name	PWM16n	ECOMn	CAPPn	CAPNn	MATn	TOGn	PWMn	ECCFn
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Addresses: 0xDA (n = 0), 0xDB (n = 1), 0xDC (n = 2), 0xDD (n = 3), 0xDE (n = 4)

SFR Pages: All Pages (n = 0), All Pages (n = 1), All Pages (n = 2), All Pages (n = 3), All Pages (n = 4)

Bit	Name	Function
7	PWM16n	16-bit Pulse Width Modulation Enable.
		This bit enables 16-bit mode when Pulse Width Modulation mode is enabled. 0: 8-bit PWM selected. 1: 16-bit PWM selected.
6	ECOMn	Comparator Function Enable.
		This bit enables the comparator function for PCA module n when set to 1.
5	CAPPn	Capture Positive Function Enable.
		This bit enables the positive edge capture for PCA module n when set to 1.
4	CAPNn	Capture Negative Function Enable.
		This bit enables the negative edge capture for PCA module n when set to 1.
3	MATn	Match Function Enable.
		This bit enables the match function for PCA module n when set to 1. When enabled, matches of the PCA counter with a module's capture/compare register cause the CCFn bit in PCA0MD register to be set to logic 1.
2	TOGn	Toggle Function Enable.
		This bit enables the toggle function for PCA module n when set to 1. When enabled, matches of the PCA counter with a module's capture/compare register cause the logic level on the CEXn pin to toggle. If the PWMn bit is also set to logic 1, the module operates in Frequency Output Mode.
1	PWMn	Pulse Width Modulation Mode Enable.
		This bit enables the PWM function for PCA module n when set to 1. When enabled, a pulse width modulated signal is output on the CEXn pin. 8-bit PWM is used if PWM16n is cleared; 16-bit mode is used if PWM16n is set to logic 1. If the TOGn bit is also set, the module operates in Frequency Output Mode.
0	ECCFn	Capture/Compare Flag Interrupt Enable.
		This bit sets the masking of the Capture/Compare Flag (CCFn) interrupt.
		1: Enable a Capture/Compare Flag interrupt request when CCFn is set.
Note:	When the W watchdog ti Timer must	VDTE bit is set to 1, the PCA0CPM4 register cannot be modified, and module 4 acts as the mer. To change the contents of the PCA0CPM4 register or the function of module 4, the Watchdog be disabled.



SFR Definition 26.4. PCA0L: PCA Counter/Timer Low Byte

Bit	7	6	5	4	3	2	1	0
Name	PCA0[7:0]							
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xF9; SFR Page = All Pages

Bit	Name	Function			
7:0	PCA0[7:0]	PCA Counter/Timer Low Byte.			
		The PCA0L register holds the low byte (LSB) of the 16-bit PCA Counter/Timer.			
Note:	 When the WDTE bit is set to 1, the PCA0L register cannot be modified by software. To change the contents of the PCA0L register, the Watchdog Timer must first be disabled. 				

SFR Definition 26.5. PCA0H: PCA Counter/Timer High Byte

Bit	7	6	5	4	3	2	1	0
Name	PCA0[15:8]							
Туре	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

SFR Address = 0xFA; SFR Page = All Pages

Bit	Name	Function				
7:0	PCA0[15:8]	PCA Counter/Timer High Byte.				
		The PCA0H register holds the high byte (MSB) of the 16-bit PCA Counter/Timer. Reads of this register will read the contents of a "snapshot" register, whose contents are updated only when the contents of PCA0L are read (see Section 26.1).				
Note:	When the WDTE bit is set to 1, the PCA0H register cannot be modified by software. To change the contents of the PCA0H register, the Watchdog Timer must first be disabled.					



C2 Register Definition 27.4. FPCTL: C2 Flash Programming Control

Bit	7	6	5	4	3	2	1	0
Name	FPCTL[7:0]							
Туре	R/W							
Reset	0	0	0	0	0	0	0	0

C2 Address: 0x02

Bit	Name	Function
7:0	FPCTL[7:0]	Flash Programming Control Register.
		This register is used to enable Flash programming via the C2 interface. To enable C2 Flash programming, the following codes must be written in order: 0x02, 0x01. Note that once C2 Flash programming is enabled, a system reset must be issued to resume normal operation.

C2 Register Definition 27.5. FPDAT: C2 Flash Programming Data

Bit	7	6	5	4	3	2	1	0
Name	FPDAT[7:0]							
Туре	R/W							
Reset	0	0	0	0	0	0	0	0

C2 Address: 0xAD

Bit	Name	Function					
7:0	FPDAT[7:0]	C2 Flash Program	C2 Flash Programming Data Register.				
		This register is use accesses. Valid co	ed to pass Flash commands, addresses, and data during C2 Flash mmands are listed below.				
		Code	Command				
		0x06	Flash Block Read				
		0x07	Flash Block Write				
		0x08	Flash Page Erase				
		0x03	Device Erase				



28. Revision Specific Behavior

This chapter contains behavioral differences between the C8051F388/9/A/B hardware revisions and behavior as stated in the data sheet.

28.1. Revision Identification

The Lot ID Code on the top side of the device package can be used for decoding device revision information. On C8051F388/9/A/B devices, the revision letter is the first letter of the Lot ID Code.

Figure 28.1, Figure 28.2, and Figure 28.3 show how to find the Lot ID Code on the top side of the device package.



Figure 28.1. Device Package – TQFP48

